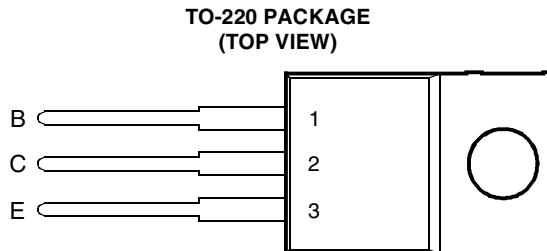


- Rugged Triple-Diffused Planar Construction
- 4 A Continuous Collector Current
- Operating Characteristics Fully Guaranteed at 100°C
- 1200 Volt Blocking Capability
- 75 W at 25°C Case Temperature



Pin 2 is in electrical contact with the mounting base.

MDTRACA

#### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ( $I_E = 0$ )	TIPL760B TIPL760C	$V_{CBO}$	1100 1200	V
Collector-emitter voltage ( $V_{BE} = 0$ )	TIPL760B TIPL760C	$V_{CES}$	1100 1200	V
Collector-emitter voltage ( $I_B = 0$ )	TIPL760B TIPL760C	$V_{CEO}$	500 550	V
Emitter-base voltage		$V_{EBO}$	10	V
Continuous collector current		$I_C$	4	A
Peak collector current (see Note 1)		$I_{CM}$	8	A
Continuous device dissipation at (or below) 25°C case temperature		$P_{tot}$	75	W
Operating junction temperature range		$T_j$	-65 to +150	°C
Storage temperature range		$T_{stg}$	-65 to +150	°C

NOTE 1: This value applies for  $t_p \leq 10$  ms, duty cycle  $\leq 2\%$ .

#### PRODUCT INFORMATION

# TIPL760B, TIPL760C NPN SILICON POWER TRANSISTORS

**BOURNS®**

## electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
$V_{CEO(sus)}$	$I_C = 10 \text{ mA}$	$L = 25 \text{ mH}$	(see Note 2)	TIPL760B TIPL760C	500 550			V
$I_{CES}$	$V_{CE} = 1100 \text{ V}$	$V_{BE} = 0$		TIPL760B		50		
	$V_{CE} = 1200 \text{ V}$	$V_{BE} = 0$		TIPL760C		50		
	$V_{CE} = 1100 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL760B		200		$\mu\text{A}$
	$V_{CE} = 1200 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL760C		200		
$I_{CEO}$	$V_{CE} = 500 \text{ V}$	$I_B = 0$		TIPL760B		50		
	$V_{CE} = 550 \text{ V}$	$I_B = 0$		TIPL760C		50		$\mu\text{A}$
$I_{EBO}$	Emitter cut-off current	$V_{EB} = 10 \text{ V}$	$I_C = 0$			1		mA
$h_{FE}$	Forward current transfer ratio	$V_{CE} = 5 \text{ V}$	$I_C = 0.5 \text{ A}$	(see Notes 3 and 4)	20		60	
$V_{CE(sat)}$	$I_B = 0.4 \text{ A}$	$I_C = 2 \text{ A}$				1.0		
	$I_B = 0.6 \text{ A}$	$I_C = 3 \text{ A}$	(see Notes 3 and 4)			2.5		V
	$I_B = 0.6 \text{ A}$	$I_C = 3 \text{ A}$	$T_C = 100^\circ\text{C}$			5.0		
$V_{BE(sat)}$	$I_B = 0.4 \text{ A}$	$I_C = 2 \text{ A}$				1.2		
	$I_B = 0.6 \text{ A}$	$I_C = 3 \text{ A}$	(see Notes 3 and 4)			1.4		V
	$I_B = 0.6 \text{ A}$	$I_C = 3 \text{ A}$	$T_C = 100^\circ\text{C}$			1.3		
$f_t$	Current gain bandwidth product	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ MHz}$		12		MHz
$C_{ob}$	Output capacitance	$V_{CB} = 20 \text{ V}$	$I_E = 0$	$f = 0.1 \text{ MHz}$		110		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques,  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

## thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1.56	°C/W

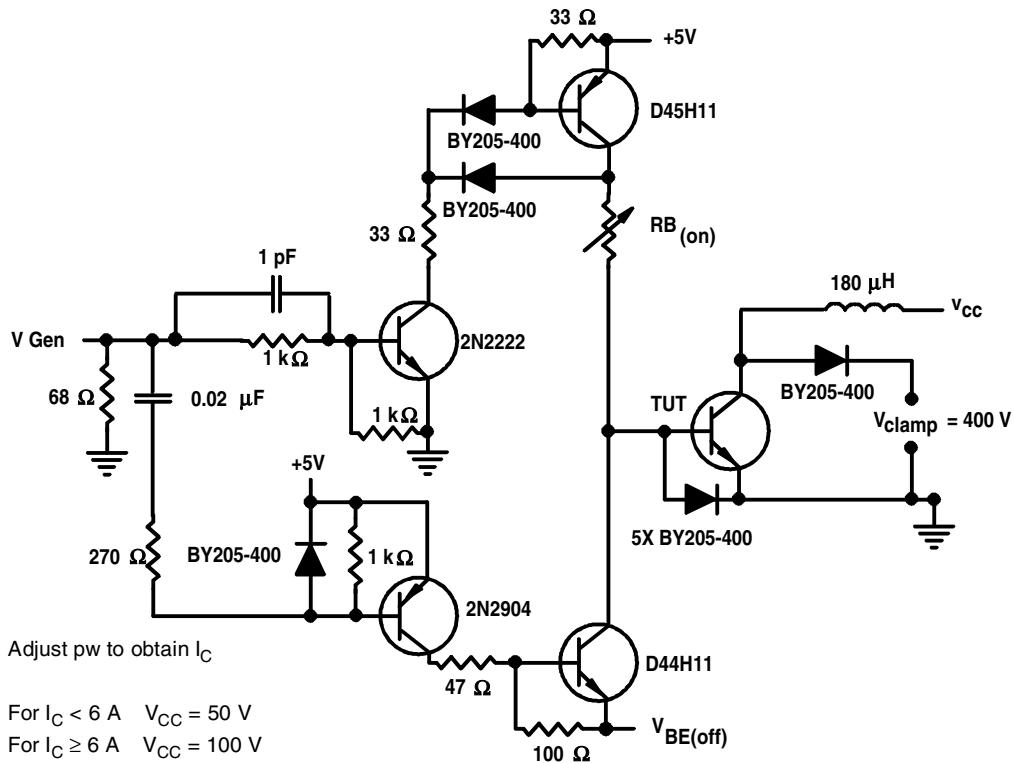
## inductive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>			MIN	TYP	MAX	UNIT
$t_{sv}$	$I_C = 3 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 0.6 \text{ A}$ (see Figures 1 and 2)				2.5	$\mu\text{s}$
$t_{rv}$						300	ns
$t_{fi}$						250	ns
$t_{ti}$						150	ns
$t_{xo}$						400	ns
$t_{sv}$	$I_C = 3 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 0.6 \text{ A}$ $T_C = 100^\circ\text{C}$ (see Figures 1 and 2)				3	$\mu\text{s}$
$t_{rv}$						500	ns
$t_{fi}$						250	ns
$t_{ti}$						150	ns
$t_{xo}$						750	ns

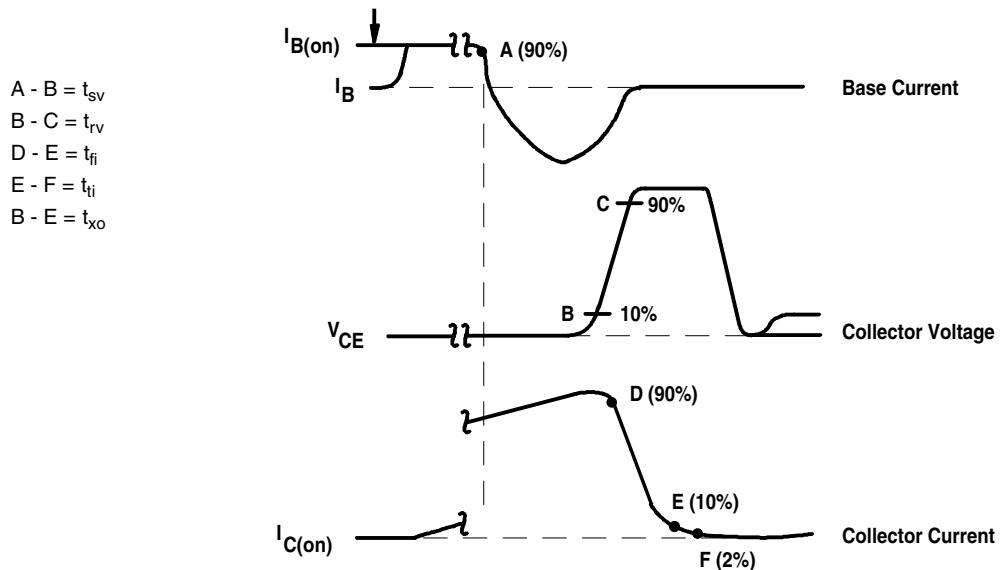
<sup>†</sup> Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

## PRODUCT INFORMATION

## PARAMETER MEASUREMENT INFORMATION



**Figure 1. Inductive-Load Switching Test Circuit**



NOTES: A. Waveforms are monitored on an oscilloscope with the following characteristics:  $t_r < 15$  ns,  $R_{in} > 10 \Omega$ ,  $C_{in} < 11.5$  pF.  
B. Resistors must be noninductive types.

**Figure 2. Inductive-Load Switching Waveforms**

## **PRODUCT INFORMATION**

MAY 1989 - REVISED SEPTEMBER 2002  
Specifications are subject to change without notice.

### TYPICAL CHARACTERISTICS

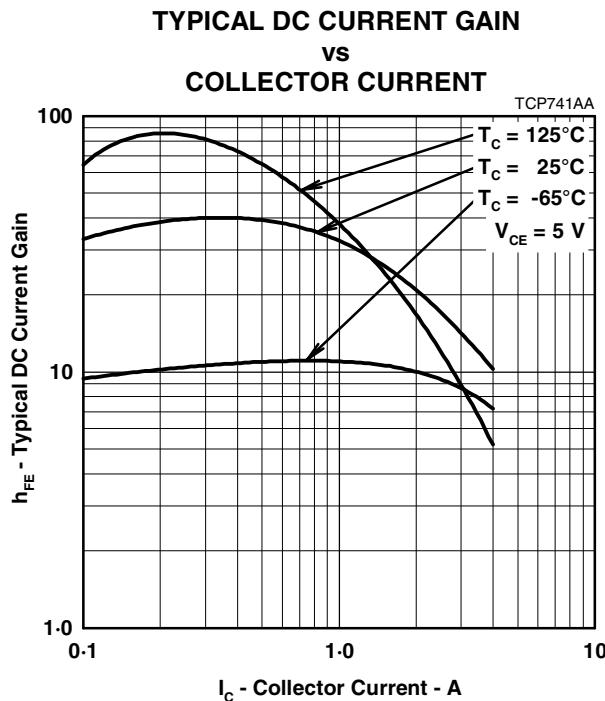


Figure 3.

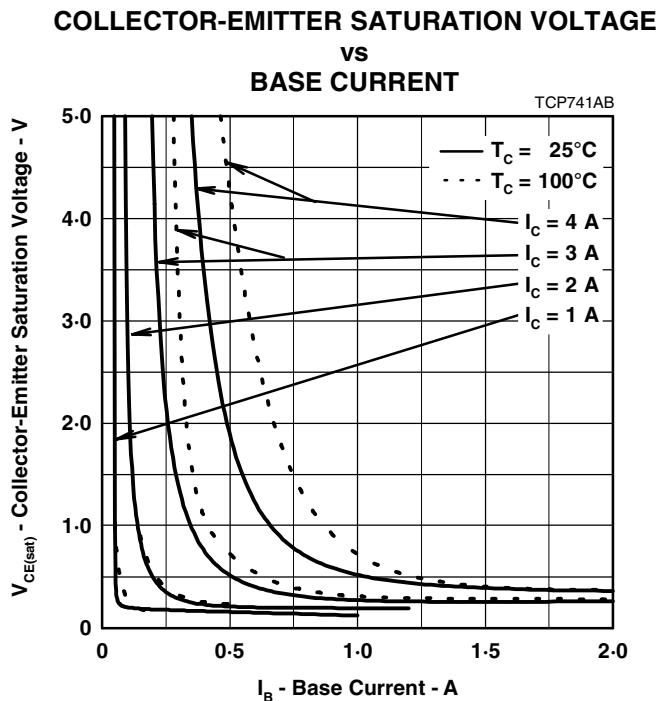


Figure 4.

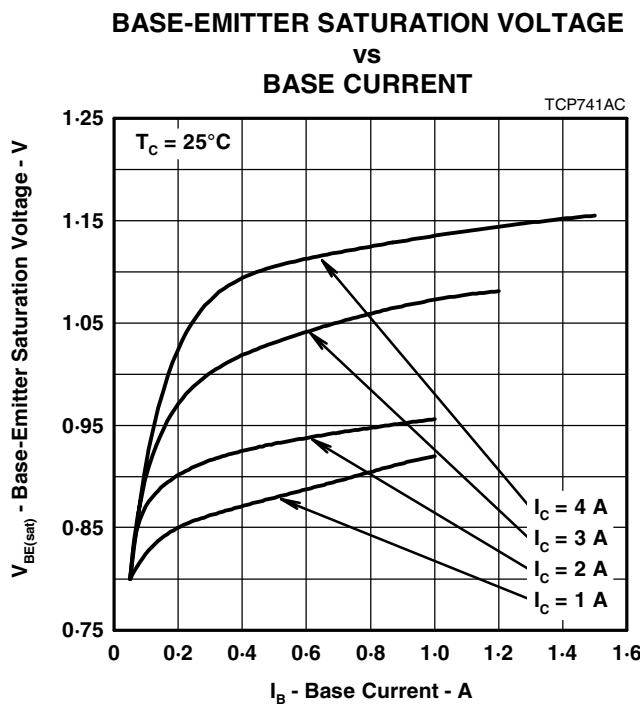


Figure 5.

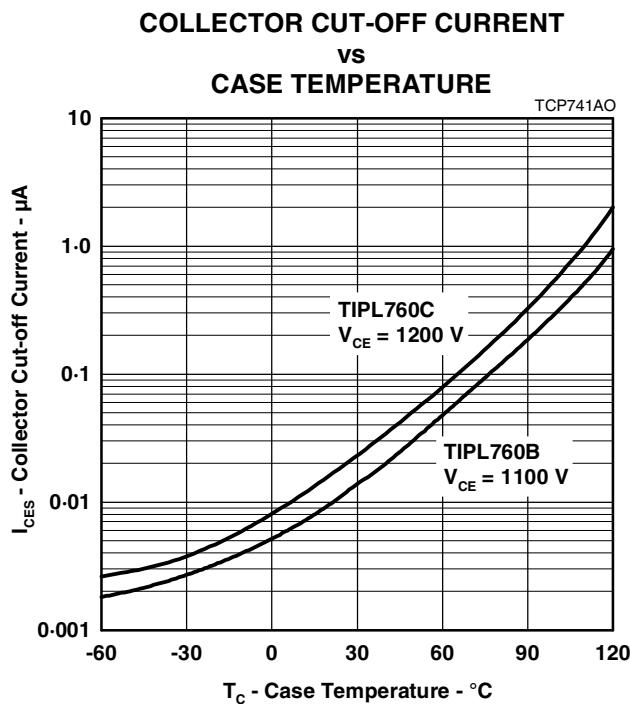


Figure 6.

### PRODUCT INFORMATION

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## MAXIMUM SAFE OPERATING REGIONS

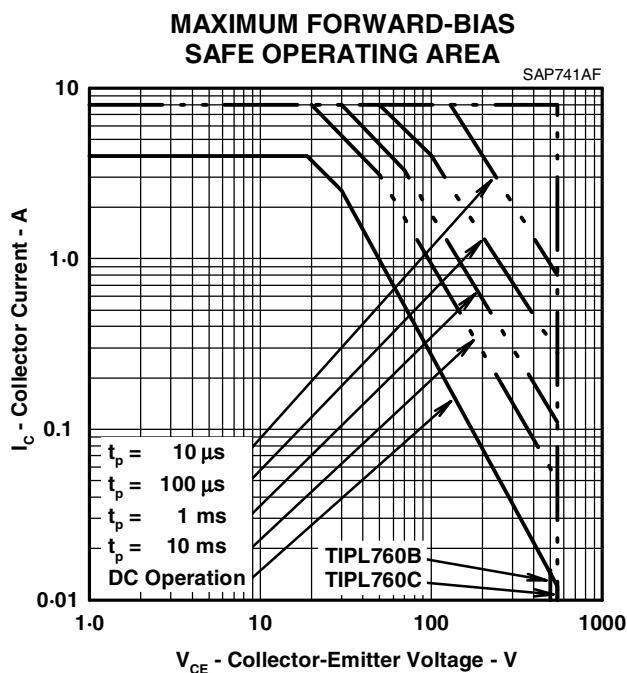


Figure 7.

## THERMAL INFORMATION

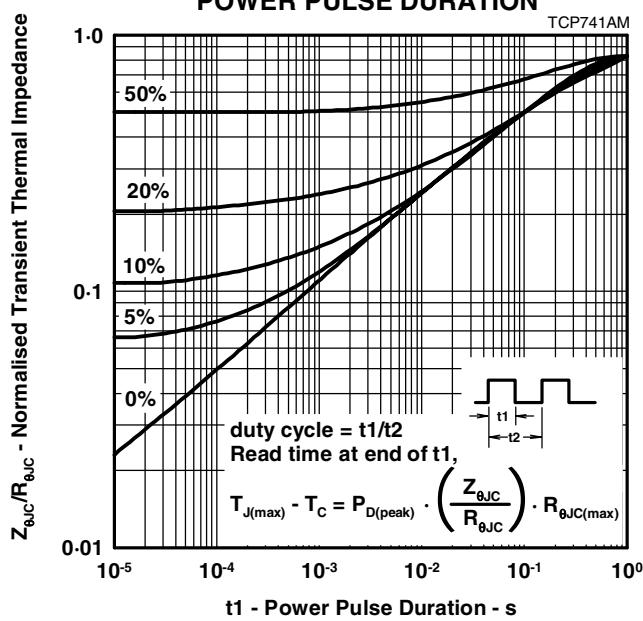
THERMAL RESPONSE JUNCTION TO CASE  
vs  
POWER PULSE DURATION

Figure 8.

## PRODUCT INFORMATION

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